SPEC.No. ASDIQ-SPE-117( Date: Aug.27,2022  To:						
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To:				5	SPEC.No.	
	To:					
CUSTOMER'S PRODUCT NAME		CUSTOMI	ER'S PRODUC	T NAME		
ASDI PRODUCT NAME:  SPUI75N-SERIES						
RECEIPT CONFIRMATION  UNCONDITIONAL CONSENT  CONDITIONAL CONSENT	UNCONDITION	AL CONSENT				CONSENT
APPROVED CHECKED		PPROVED		Cł	HECKED	
ASDI SIGNATURE  APPROVED CHECKED PREPARED  Xianglong Li Liang Wang Jiayin Cai	A					



REV.	DATE	DESCRIPTION	APPROVED	CHECKED	PREPARED
00	Aug.27,2022	New release	Xianglong Li	Liang Wang	Jiayin Cai

# **CAUTION WHEN HANDLING**

Before use the products, please read this specification.

# **CAUTION FOR SAFETY USING**

When use the products, be careful to mentioned below for safety using.

# **CAUTION**

\*The product should be used within 12 monthes.

Focus on the storage conditions.

Solderability may become weak if it exceeds the period.

\*Do not use and store the product in condition of gas corrosion (Salt,Acid,Alkaline).

\*The products must be preheated before soldering.

The operating temperature including self-generated heat must be within '-40~+125  $^{\circ}$ C

\*Rework by soldering iron; Please keep the mentioned conditions in this specification.

\*In case of insert P.C. Board on chassis, do not add mechanical stress to the product.

\*Be careful to arrange of non-magnetic field type inductors.

The error may be caused by magnetic field coupling.

\*In case handle the products, please use wrist strap for ground static discharge on human body.

The product keeps away from magnet or magnetized things.

\*Do not use the product beyond the mentioned conditions in this specification.

\*About an application

The products listed on this specification sheet are intended for use in general electronic equipment

(AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.

\*The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet.

1)Aerospace/Aviation equipment
2)Military equipment
3)Seabed equipment
4)Safety equipment
5)Medical equipment
2)Transportation control equipment
7)Power-generation control equipment
which directly endanger human life
8)Atomic energy-related equipment
9)Other applications that are not

considered general-purpose applications

If you intend to use the products in the following applications, please contact our sales office. Transportation equipment (cars, electric trains, ships, etc.), Public information-processing equipment, Electric heating apparatus / burning equipment, Disaster prevention/crime prevention equipment

When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.

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**ISSUE** 

CUSTOMER	ASDI PART No.	CUSTOMER'S DWG NO.
	SPUI75N-SERIES	

## 1.INDEX

Listed item	Attachment&Tables	Page
1.Features	Please see (1)	3/7
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4.Part Numbering	Please see (4)	3/7
5.Electrical Specifications	Please see (5)	4/7
6.Structure and Components	Please see (6)	5/7
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# 2.Manufacturing Location

China

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Xiamen ASDI Electronics Co.,Ltd.					

## (1)Features

- 1.Small and Low profile inductor
- 2.It corresponds to high current.
- 3. Simple and Shield structure.
- 4. Available tape and reel for auto insertion.
- 5.100% Lead(Pb)-Free and RoHS compliant.



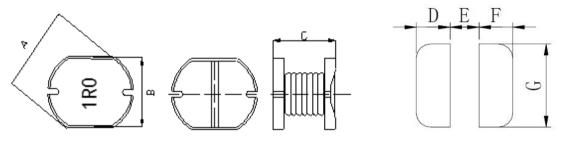


## (2)Applications

-For small DC/DC converter(cellular phone,LCD/LED/OLED display, HDD, DSC etc)

## (3)Dimensions

## Recommendend Land pattern



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
SPUI75N	7.8±0.3	7.0±0.3	5.0±0.4	3.0	2.0	3.0	7.5

## (4)Part Numbering

SPUI	75	N	-	1R0	M
Α	В	С		D	Ε

A: Series

**B**: Dimension

C: Type

D: Inductance  $1R0=1.0\mu H, 100=10\mu H, 101=100\mu H, 102=1000\mu H$ 

E: Inductance Tolerance K=±10% M=±20%

marking direction cannot decide polarity. Color: Black,

unidirectional.

No magnetic shielding

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Xiamen ASDI Electronics Co.,Ltd.

## (5)Electrical Specification

	Inductance			Rated current		DCR		
ASDI Part Number	L0 (uH)	Tolerance	Frequency	Saturation	Tempetature	(mΩ) @25°C		
AODIT art Number	@ 0 A	roicianice	(Hz/0.25V)	current I sat (A)	current I rms (A)	±20%.		
SPUI75N-1R0M	1.00	±20%	100K	8.50	8.00	10.0		
SPUI75N-1R5M	1.50	±20%	100K	5.80	4.50	25.0		
SPUI75N-2R2M	2.20	±20%	100K	5.50	4.15	25.0		
SPUI75N-3R3M	3.30	±20%	100K	5.10	3.85	30.0		
SPUI75N-4R7M	4.70	±20%	100K	4.70	3.50	38.0		
SPUI75N-5R6M	5.60	±20%	100K	4.15	3.20	45.0		
SPUI75N-6R8M	6.80	±20%	100K	3.75	2.80	48.0		
SPUI75N-8R2M	8.20	±20%	100K	3.60	2.50	49.0		
SPUI75N-100M	10.00	±20%	100K	3.50	2.10	50.0		
SPUI75N-150M	15.00	±20%	100K	2.75	1.75	100		
SPUI75N-220M	22.00	±20%	100K	2.40	1.50	120		
SPUI75N-330K,M	33.00	±10%/±20%	100K	1.80	1.30	150		
SPUI75N-470K,M	47.00	±10%/±20%	100K	1.60	1.10	200		
SPUI75N-680K,M	68.00	±10%/±20%	100K	1.15	0.80	300		
SPUI75N-101K	100.0	±10%	100K	0.87	0.65	450		
SPUI75N-121K	120.0	±10%	100K	0.73	0.60	490		
SPUI75N-151K	150.0	±10%	100K	0.58	0.45	640		
SPUI75N-181K	180.0	±10%	100K	0.70	0.55	730		
SPUI75N-221K	220.0	±10%	100K	0.65	0.47	1000		
SPUI75N-331K	330.0	±10%	100K	0.57	0.40	1450		
SPUI75N-471K	470.0	±10%	100K	0.43	0.32	2050		
SPUI75N-561M	560.0	±20%	100K	0.40	0.31	2400		
SPUI75N-681K	680.0	±10%	100K	0.38	0.30	2900		
SPUI75N-821K	820.0	±10%	100K	0.30	0.28	3250		
SPUI75N-102K	1000.0	±10%	100K	0.30	0.26	3500		
SPUI75N-152K	1500.0	±10%	100K	0.15	0.20	5300		
	K±10% M±20%							

- 2.Testing Instrument : L/Q: HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
- 3.Heat Rated Current (Irms) will cause the coil temperature rise approximately  $\Delta t$  of 40  $^{\circ}{\rm C}$  (keep 1min.).
- 4.Saturation Current (Isat) will cause L0 to drop 30% typical. (keep quickly).

  5.The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
- 6. Special inquiries besides the above common used types can be met on your requirement.

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o	nics CoLtd.		

## (6)Structure and Components

No.	Components	Material
1	Core	Ferrite core.
2	Wire	Polyester Wire or equivalent.
3	Ink	Halogen-free ketone



## (7)Reliability Tests

No.	Test item	Performance	Test details
1	Operating temperature	-40~+125℃	
2	Storage Temperature	-10~+40°C,50~60%RH (Product without taping)	
		Electrical Performance T	Fest
3	Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320SLCR Meter.
4	DCR		CH16502,Agilent33420A Micro-Ohm Meter.
5	Saturation Current (Isat)	△L30% typical.	Saturation DC Current (Isat) will cause L0 to drop $\triangle$ L(%)(keep quickly).
6	Heat Rated Current (Irms)	Approximately △T ≦ 40 °C	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(^{\circ}C)$ without core loss. 1.Applied the allowed DC current(keep 1 min.). 2.Temperature measured by digital surface thermometer
		Reliability Test	
7	High Temperature Exposure Test		Temperature:125±2°C. Duration:1000±12hrs. Measured at room temperature after placing for 2 to 3hrs. (MIL-PRF-27)
8	Low Temperature Life Test		Temperature:-40±2°C. Duration:500±12hrs. Measured at room temperature after placing for 2 to 3hrs.
9	Biased Humidity Test		Humidity:85±3%RH. Temperature:85±2°C. Duration:1000±12hrs. Measured at room temperature after placing for 2 to 3hrs (AEC-Q200-REV C)
10	Thermal shock test	Electric specifications should be satisfied	Condition for 1 cycle $Step1:-40+0 \ / \ -2 \ \ \ \ 15\pm 1 \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ $
11	Vibration test		Frequency: 10-2000-10Hz for 20 min.  Amplitude: Parts mounted within 2" from any secure point.  Directions and times: X, Y, Z directions for 20 min.  This cycle shall be performed 12 times in each of three mutually perpendicular directions(Total 12 hours).  (MIL-STD-202 Method 204 D Test condition B)
12	Reflow test		Pre-heat: $150\pm5^{\circ}$ C Duration: 5 minutes Temperature: $260\pm5^{\circ}$ C, $20\sim40$ seconds (IPC/JEDEC J-STD-020C)
13	Solder test	Terminals should be covered by over 95% solder on visual inspection	After dip into flux, dip into solder 235±5℃, 4±1seconds Flux 、solder for lead free (ANSI /J-STD-002C Method B)

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## (8) Soldering and Mounting

## 8-1, Soldering

Mildly activated rosin fluxes are preferred.

The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate.

ASDI terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

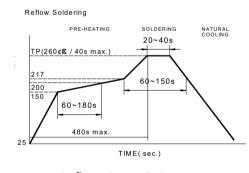
## 8-2, Solder re-flow

Recommended temperature profiles for re-flow soldering in Figure 1.

## 8-3, Soldering Iron

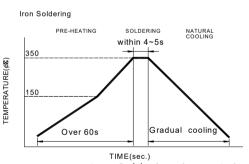
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- ·Preheat circuit and products to 150°C
- ·Never contact the ceramic with the iron tip
- ·Use a 20 watt soldering iron with tip diameter of 1.0mm
- ·355°C tip temperature (max)
- ·1.0mm tip diameter (max)
- ·Limit soldering time to 4-5sec.



Reflow times: 3 times

Fig.1



Iron Soldering times: 1 times

Fig.2

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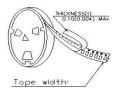
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Xiamen ASDI Electronics Co., Ltd.

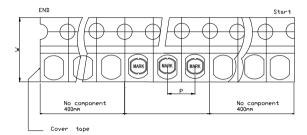
## (9)Packaging Information

## 9-1,Reel Dimension





## 9-2, Tape Dimension



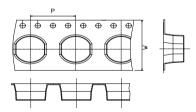
Unreeling Direction

Note: After the tape is woven, the outermost layer of the reel is 400mmMIN, and the innermost layer is 400mmMIN.

## 9-3, Packaging Quantity

SPUI	75
Chip / Reel	1000

## 9-4, Carrier Tape Dimensions (mm)



W	16
Р	12

## (10)Note

## ·Storage Conditions

To maintain the solderability of terminal electrodes:

- 1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Temperature: 5 to 30deg.C, Humidity: 75% Max.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

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